

N-CHANNEL 60V - 0.020 Ω - 28A IPAK/DPAK STripFET™ II POWER MOSFET

TYPE	V _{DSS}	R _{DS(on)}	ID
STD30NF06	60 V	<0.028 Ω	28 A

- TYPICAL $R_{DS}(on) = 0.020\Omega$
- EXCEPTIONAL dv/dt CAPABILITY
- 100% AVALANCHE TESTED
- THROUGH-HOLE IPAK (TO-251) POWER PACKAGE IN TUBE (SUFFIX "-1")
- SURFACE-MOUNTING DPAK (TO-252) POWER PACKAGE IN TAPE & REEL (SUFFIX "T4")

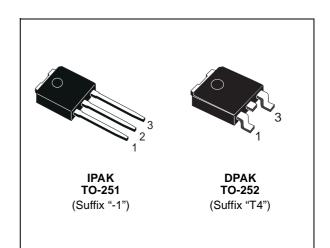
DESCRIPTION

This Power MOSFET is the latest development of STMicroelectronis unique "Single Feature SizeTM" stripbased process. The resulting transistor shows extremely high packing density for low on-resistance, rugged avalanche characteristics and less critical alignment steps therefore a remarkable manufacturing reproducibility.

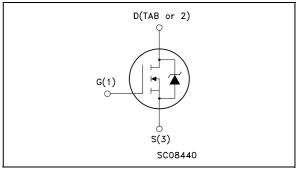
APPLICATIONS

- HIGH CURRENT, HIGH SWITCHING SPEED
- MOTOR CONTROL , AUDIO AMPLIFIERS
- SOLENOID AND RELAY DRIVERS
- DC-DC & DC-AC CONVERTERS

ABSOLUTE MAXIMUM RATINGS



INTERNAL SCHEMATIC DIAGRAM



Symbol	Parameter	Value	Unit
V _{DS}	Drain-source Voltage ($V_{GS} = 0$)	60	V
Vdgr	Drain-gate Voltage (R_{GS} = 20 k Ω)	60	V
V _{GS}	Gate- source Voltage	± 20	V
ID	Drain Current (continuous) at $T_C = 25^{\circ}C$	28	Α
ID	Drain Current (continuous) at T _C = 100°C	20	A
I _{DM} (•)	Drain Current (pulsed)	112	A
P _{tot}	Total Dissipation at $T_C = 25^{\circ}C$	70	W
	Derating Factor	0.47	W/°C
dv/dt (1)	Peak Diode Recovery voltage slope	10	V/ns
E _{AS} (2)	Single Pulse Avalanche Energy	230	mJ
T _{stg} Storage Temperature		-55 to 175	°C
Tj	Max. Operating Junction Temperature	-55 10 175	
Pulse width	limited by safe operating area.	(1) $I_{SD} \le 28A$, di/dt $\le 300A/\mu s$, $V_{DD} \le V_{(BR)DSS}$, $T_j \le$ (2) Starting T: = 25 °C, $I_D = 15A$, $V_{DD} = 30V$	T _{JMAX}

(2) Starting $T_j = 25 \text{ °C}$, $I_D = 15A$, $V_{DD} = 30V$

March 2002

1/10

THERMAL DATA

Rthj-case Rthj-amb Tl	Thermal Resistance Junction-case Thermal Resistance Junction-ambient Maximum Lead Temperature For Soldering Purpose	Max Max	2.14 100 275	°C/W °C/W °C
1	Maximum Leau Temperature For Soluening Fulpose		215	C

ELECTRICAL CHARACTERISTICS (T_{case} = 25 °C unless otherwise specified)

OFF

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
V _{(BR)DSS}	Drain-source Breakdown Voltage	$I_D = 250 \ \mu A, \ V_{GS} = 0$	60			V
I _{DSS}	Zero Gate Voltage Drain Current (V _{GS} = 0)	V_{DS} = Max Rating V_{DS} = Max Rating T _C = 100°C			1 10	μΑ μΑ
I _{GSS}	Gate-body Leakage Current (V _{DS} = 0)	V _{GS} = ± 20 V			±100	nA

ON (*)

Symbol	Parameter	Test Conditions		Min.	Тур.	Max.	Unit
V _{GS(th)}	Gate Threshold Voltage	$V_{DS} = V_{GS}$	I _D = 250 μA	2		4	V
R _{DS(on)}	Static Drain-source On Resistance	V _{GS} = 10 V	I _D = 15 A		0.020	0.028	Ω

DYNAMIC

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
g _{fs} (*)	Forward Transconductance	V _{DS} = 15 V I _D = 15 A		40		S
C _{iss} C _{oss} C _{rss}	Input Capacitance Output Capacitance Reverse Transfer Capacitance	V _{DS} = 25V, f = 1 MHz, V _{GS} = 0		1750 220 70		pF pF pF

ELECTRICAL CHARACTERISTICS (continued)

SWITCHING ON

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
t _{d(on)} t _r	Turn-on Delay Time Rise Time			20 100		ns ns
Q _g Q _{gs} Q _{gd}	Total Gate Charge Gate-Source Charge Gate-Drain Charge	V _{DD} = 48V I _D = 38A V _{GS} = 10V		43 9.5 15	58	nC nC nC

SWITCHING OFF

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
t _{d(off)} t _f	Turn-off Delay Time Fall Time			50 20		ns ns

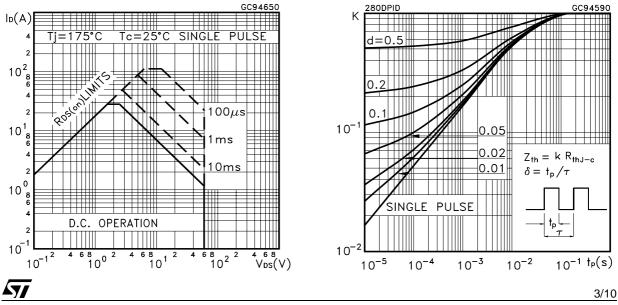
SOURCE DRAIN DIODE

Symbol	Parameter	Test Co	Test Conditions		Тур.	Max.	Unit
I _{SD} I _{SDM} (●)	Source-drain Current Source-drain Current (pulsed)					28 112	A A
V _{SD} (*)	Forward On Voltage	I _{SD} = 28 A	$V_{GS} = 0$			1.5	V
t _{rr} Q _{rr} I _{RRM}	Reverse Recovery Time Reverse Recovery Charge Reverse Recovery Current	$I_{SD} = 28 \text{ A}$ $V_{DD} = 30 \text{ V}$ (see test circu	di/dt = 100A/µs T _j = 150°C it, Figure 5)		95 260 5.5		ns μC Α

(*)Pulsed: Pulse duration = 300 μ s, duty cycle 1.5 %.

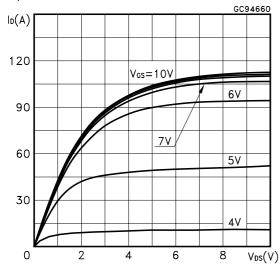
(•)Pulse width limited by safe operating area.

Safe Operating Area

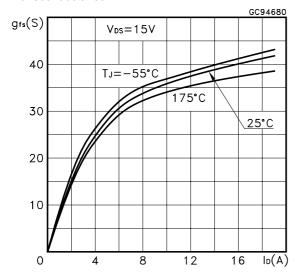


Thermal Impedance

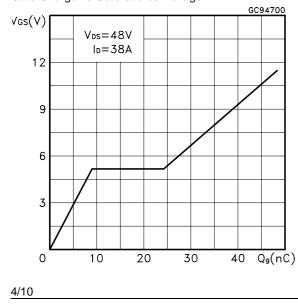
Output Characteristics



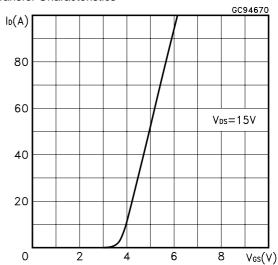
Transconductance

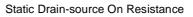


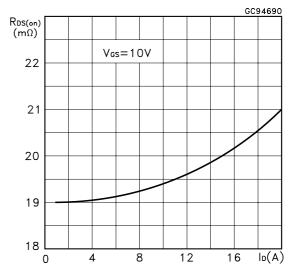




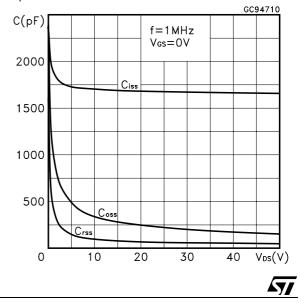


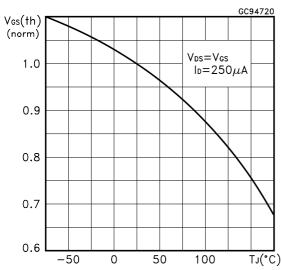






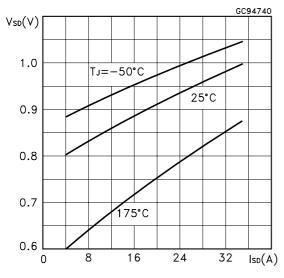
Capacitance Variations



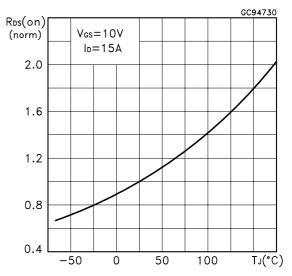


Normalized Gate Threshold Voltage vs Temperature

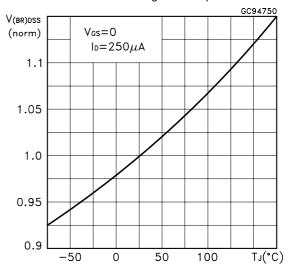
Source-drain Diode Forward Characteristics



Normalized on Resistance vs Temperature



Normalized Breakdown Voltage vs Temperature



57

Fig. 1: Unclamped Inductive Load Test Circuit

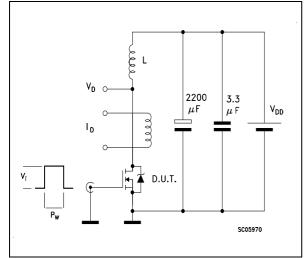
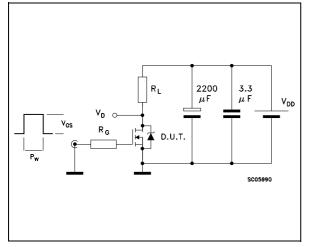
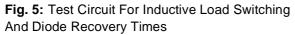
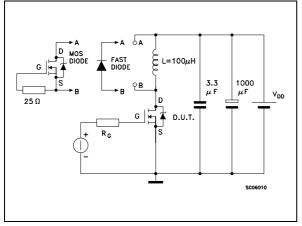


Fig. 3: Switching Times Test Circuits For Resistive Load







6/10

Fig. 2: Unclamped Inductive Waveform

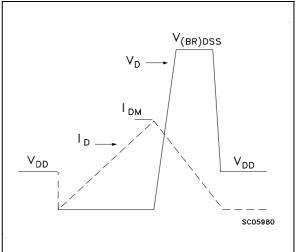
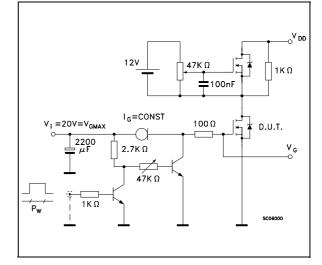


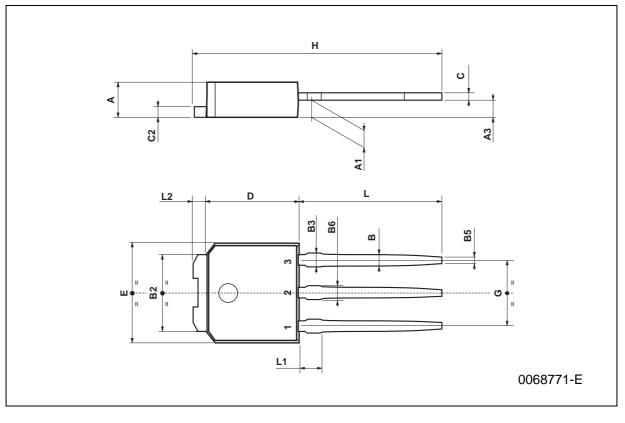
Fig. 4: Gate Charge test Circuit





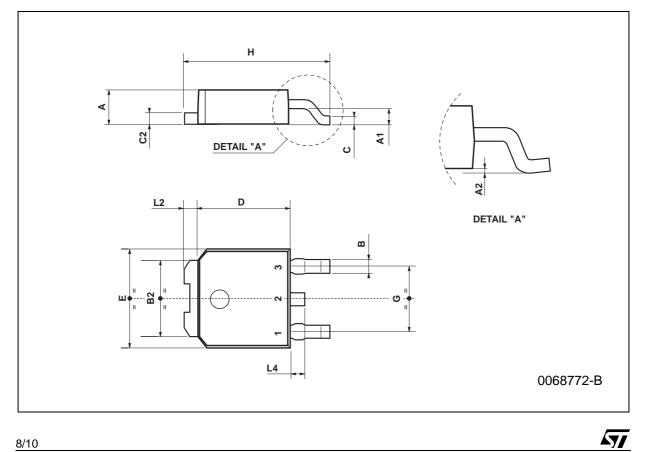
DIM.		mm			inch	
DINI.	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
А	2.2		2.4	0.086		0.094
A1	0.9		1.1	0.035		0.043
A3	0.7		1.3	0.027		0.051
В	0.64		0.9	0.025		0.031
B2	5.2		5.4	0.204		0.212
B3			0.85			0.033
B5		0.3			0.012	
B6			0.95			0.037
С	0.45		0.6	0.017		0.023
C2	0.48		0.6	0.019		0.023
D	6		6.2	0.236		0.244
Е	6.4		6.6	0.252		0.260
G	4.4		4.6	0.173		0.181
Н	15.9		16.3	0.626		0.641
L	9		9.4	0.354		0.370
L1	0.8		1.2	0.031		0.047
L2		0.8	1		0.031	0.039

TO-251 (IPAK) MECHANICAL DATA

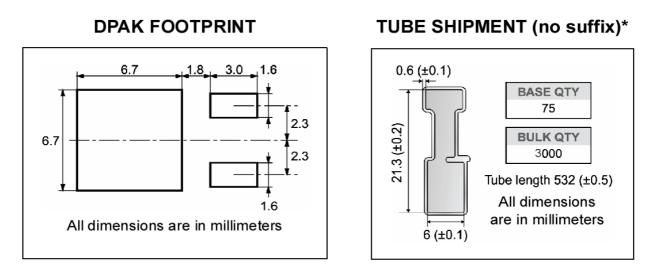


DIM.		mm		inch		
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
А	2.2		2.4	0.086		0.094
A1	0.9		1.1	0.035		0.043
A2	0.03		0.23	0.001		0.009
В	0.64		0.9	0.025		0.035
B2	5.2		5.4	0.204		0.212
С	0.45		0.6	0.017		0.023
C2	0.48		0.6	0.019		0.023
D	6		6.2	0.236		0.244
E	6.4		6.6	0.252		0.260
G	4.4		4.6	0.173		0.181
н	9.35		10.1	0.368		0.397
L2		0.8			0.031	
L4	0.6		1	0.023		0.039

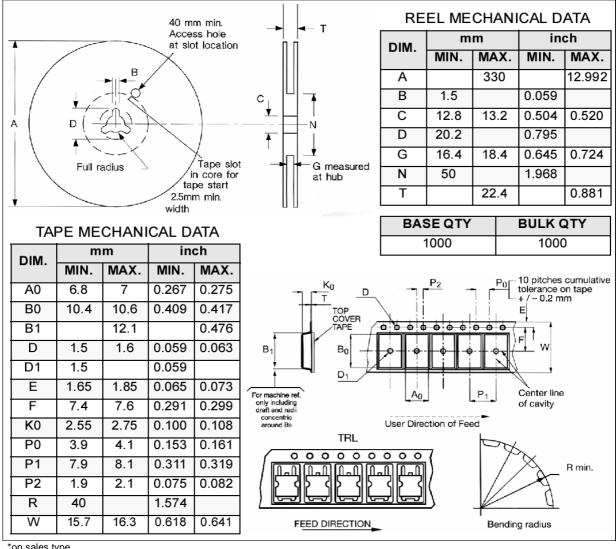








TAPE AND REEL SHIPMENT (suffix "T4")*



*on sales type

47/

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10/10